

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. FABRICATE IN ACCORDANCE WITH IPC-6018B, PER IPC-6011, CLASS 2.
2. ARTWORK FORMAT: GERBER 274X
GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS
COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR.
3. MATERIAL:
NUMBER OF LAYERS: 3 LAYERS
SILKSCREEN TOP: HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK
SOLDERMASK TOP: LPI (LIQUID PHOTO-IMAGEABLE), GREEN OR LDI (LASER DIRECT IMAGEABLE), GREEN. MAX FINISH
THICKNESS OF SOLDERMASK TO BE 0.001in.
METAL 1 (TOP): 0.5 oz TO START, 1.0 oz. FINISH. 2.0 oz WHEN EXTRA PLATING CYCLE AFTER COIN INSERTION.
PREPREG ROGERS 6202, 0.005 inch THICK
METAL 2 0.5 oz (PLATE TO 1.0 oz)
CORE FR4, 0.028 inch (0.7 mm) THICK
METAL 3 (BOTTOM): 0.5 oz TO START, 1.0 oz. FINISH. 2.0 oz WHEN EXTRA PLATING CYCLE AFTER COIN INSERTION.
4. FINISH PLATING:
IMMERSION SILVER per IPC-4553A, (6 - 18µm)
5. FINISHED BOARD:
THICKNESS: 0.0376 inch ±0.003
6. COPPER IS PULLED BACK PER GERBER DATA FROM EDGE OF BOARD ON METAL 1 (TOP)
AND METAL 2 (INTERNAL) EXCEPT AROUND CONNECTOR AREA. COPPER IS PULLED BACK
PER GERBER DATA FROM EDGE OF BOARD ON METAL 3 (BOTTOM).
7. PC BOARD OUTLINE TOLERANCE: ±0.002 inch (0.051 mm)
8. METALIZATION MUST BE FREE FROM CONTAMINATION AND DEBRIS.
9. BURRS SHALL NOT EXCEED 0.002 inch (0.051 mm).
10. VIA PLATING/FILLING:
A. PLATING TO BE 0.0007 inch (0.018 mm) MIN. THICKNESS UNLESS PLATED CLOSED.
B. THRU-HOLE VIAS: LAYERS 1-3
11. METAL 1 TOP AND METAL 3 BOTTOM SHALL BE PLANARIZED AFTER PLATING HOLES SHUT.
MAX ALLOWABLE NEGATIVE FEATURE 0.0008in. MAX ALLOWABLE POSITIVE FEATURE 0.0003in.
12. SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST ON BACKSIDE OF BOARD.
13. CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.003 inch (0.076 mm) OF CAD DATABASE.
14. ALL HOLES TO BE LOCATED WITHIN ±0.003 inch OF CAD DATABASE.
15. NO VENDOR MARKING OR SERIALIZATION ALLOWED.
16. DELIVER BOARDS BAGGED AS: SINGLES.
17. NO ELECTRICAL TEST NEEDED.

Drill Table - Top to Bottom (*.Txt)

Symbol	Count	Hole Size	Plated	Drill Layer Pair
A	500	0.010(0.25)	Plated	METAL_1_TOP - METAL_3_BOT
C	4	0.100(2.54)	Plated	METAL_1_TOP - METAL_3_BOT
D	2	0.160(4.06)	Plated	METAL_1_TOP - METAL_3_BOT
506 Total				

Drill Table - Top to Metal 2 (*.Tx2)

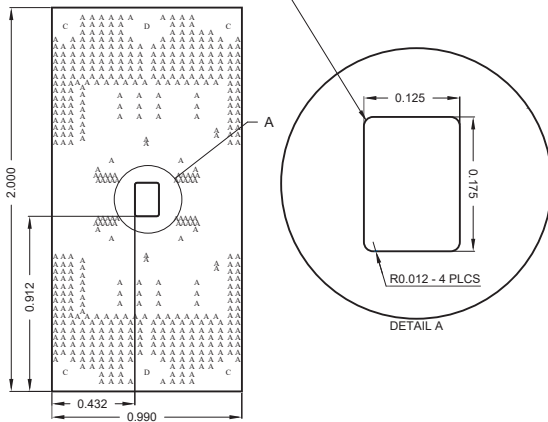
Symbol	Count	Hole Size	Plated	Drill Layer Pair
A	132	0.010(0.25)	Plated	METAL_1_TOP - METAL_2_MID
B	4	0.114(2.89)	Plated	METAL_1_TOP - METAL_2_MID
136 Total				

SUPPLIER MUST SEND EMAIL TO EVBHOLD@QORVO.COM IF JOB IS PLACED ON HOLD
SUPPLIER SHALL SEND A COPY OF FINAL WORKING GERBERS TO CEADS@QORVO.COM

LAYER STACK LEGEND

Material	Layer	Thickness	Dielectric Material	Type	Gerber
Surface Material	Top Overlay			Legend	GTO
Copper	Top Solder	0.0004in	Solder Resist	Solder Mask	GTS
Prepreg	METAL_1_TOP	0.0028in		Signal	GTL
CF-004	METAL_2_MID	0.0050in	Rogers 6202	Dielectric	
Prepreg		0.0017in		Signal	G1
Core		0.0050in	370HR	Dielectric	
Copper	METAL_3_BOT	0.0210in	LAM 370HR	Dielectric	
		0.0017in		Signal	GBL
Total thickness: 0.0376in					

Copper Coin To Be Placed in Center Of DUT
18, 19, 20, 21, 22



* FOR MULTIPLE DRILL PROCESS JOBS SEE: * DRL, *DR1, *DR2, etc.

18. COPPER COIN APERTURE TO BE EDGE PLATED, METAL 1, 2, AND METAL 3 TO BE PLATED COMPLETELY ALONG COPPER APERTURE EDGE
19. COPPER COIN MATERIAL: OXYGEN FREE HIGH CONDUCTIVITY COPPER UWS CDA 101, 102, OR 103, ASTM B187, ASTM B152.
20. COIN:
0.125 X 0.175 inch (3.175 mm X 4.445 mm) SQUARE INSERT.
FLATNESS AT COIN AREA TO BE FLUSH TO METAL 1 AND METAL 3 WITHIN +0.001/-0.001.
21. PLATING BETWEEN COPPER COIN AND METAL 1 & METAL 3 TO BE CONTINUOUS. (UNINTERRUPTED).
22. TOP OF COPPER COIN TO BE PLATED TO METAL 1. BOTTOM OF COIN TO BE PLATED TO METAL 3.

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES	SAP MATERIAL NUMBER: 293139	QORVO™	
APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE	DESIGNER: JAMES JACKSON ENGR: WAYNE BRINLEE	DATE: 11/05/19	TITLE: QPA2575 EVALUATION PCB DESIGN PACKAGE
INTERPRET DRAWING PER ANSI/ASME Y14.5 - 2009	PDE CONTROLLED	SIZE: B	DOCUMENT NUMBER: QPA2575-4000
THIRD ANGLE PROJECTION DO NOT SCALE DRAWING		PROTOTYPE INSTANCE: N/A	REV: A
		SHEET 1 OF 7	CAD: ALTIUM DESIGNER
			SCALE: 2:1

Current Date & Time: 12/19/2019 10:57

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